

**AMENDMENTS TO THE CLAIMS**

Please amend the claims as follows.

1. (Original) An electronic member fabricating method comprising:
  - an adhesive material attaching process for attaching a wafer to a thermosetting adhesive material provided on a base film;
  - a dicing-film attaching process for attaching the base film to a dicing film;
  - an IC-chip separating process for cutting the wafer and the thermosetting adhesive material to divide them into IC chips; and
  - a mounting process for attaching, to a carrier, the IC chips having the thermosetting adhesive material attached thereto;wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the adhesive material attaching process.
2. (Original) An electronic member fabricating method comprising:
  - an adhesive material attaching process for attaching a thermosetting adhesive material at least to a wafer;
  - a dicing-film attaching process for attaching a dicing film to the thermosetting adhesive material;
  - an IC-chip separating process for cutting the wafer and the thermosetting adhesive material to divide them into IC chips; and
  - a mounting process for attaching, to a carrier, the IC chips having the thermosetting adhesive material attached thereto;wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the adhesive material attaching process.
3. (Original) The electronic member fabricating method according to Claim 2, wherein the thermosetting adhesive material is covered with a base film in advance.
4. (Original) The electronic member fabricating method according to Claim 3, wherein the dicing-film attaching process includes a process for peeling the base film and a process for attaching the dicing film to the thermosetting adhesive material.

5. (Original) An electronic member fabricating method comprising:
- an adhesive material attaching process for attaching, at least to a wafer, a base film including a thermosetting adhesive material adhered thereon;
  - a cutting process for cutting the wafer and the thermosetting adhesive material to divide them into IC chips by using the base film as a dicing film; and
  - a mounting process for attaching, to a carrier, the IC chips having the thermosetting adhesive material attached thereto;
- wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the adhesive material attaching process.
6. (Currently Amended) The electronic member fabricating method according to ~~Claims 1 to 5~~ Claim 1, wherein the thermosetting adhesive material has a viscosity of 100 Pa·s or more at the attaching temperature during the adhesive material attaching process.
7. (Currently Amended) The electronic member fabricating method according to ~~Claims 1 to 6~~ Claim 1, wherein the thermosetting adhesive material does not start the heat curing reaction at the attaching temperature during the adhesive material attaching process.
8. (Currently Amended) The electronic member fabricating method according to ~~Claims 1 to 6~~ Claim 1, wherein the attaching temperature during the adhesive material attaching process is lower than the temperature that starts heat curing of the thermosetting adhesive material.
9. (Currently Amended) The electronic member fabricating method according to ~~Claims 1 to 8~~ Claim 1, wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the mounting process.
10. (Original) The electronic member fabricating method according to Claim 9, wherein the thermosetting adhesive material has a viscosity of 100 Pa·s or more at the attaching temperature during the mounting process.
11. (Currently Amended) The electronic member fabricating method according to ~~Claims 1 to 10~~ Claim 1, wherein the thermosetting adhesive material does not start the heat curing reaction at the attaching temperature during the mounting process.

12. (Currently Amended) The electronic member fabricating method according to ~~Claims 1 to 11~~ Claim 1, further comprises a process for heating the thermosetting adhesive material to cause the heat curing reaction, after the mounting process.
13. (Currently Amended) The electronic member fabricating method according to ~~Claims 1 to 12~~ Claim 1, wherein the thermosetting adhesive material is of a film type or a paste type.
14. (Currently Amended) The electronic member fabricating method according to ~~Claims 1 to 13~~ Claim 1, wherein a dicing saw is used in the cutting process.
15. (Original) An adhesive-applied IC chip including an IC chip and an adhesive material adhered to the back surface of the IC chip, wherein the adhesive material is directly attached on a base film or a dicing film, the adhesive material contains at least a thermosetting resin, the adhesive material has not started the curing reaction and the adhesive material has a viscosity of 20000 Pa·s or less at temperatures equal to or less than the curing-reaction starting temperature.
16. (Currently Amended) ~~The electronic member fabricating method~~ The adhesive-applied IC chip according to Claim 15, wherein the adhesive material has a viscosity of 100 Pa·s or more at temperatures equal to or less than the curing-reaction starting temperature.
17. (Currently Amended) The adhesive-applied IC chip according to ~~Claims 15 to 16~~ Claim 15, wherein the adhesive material starts the curing reaction at a temperature in the range of 80 to 120°C.
18. (Currently Amended) The adhesive-applied IC chip according to ~~Claims 15 to 17~~ Claim 15, wherein the adhesive material is a film-type resin.
19. (Currently Amended) The adhesive-applied IC chip according to ~~Claims 15 to 18~~ Claim 15, wherein the IC chip has a thickness of 200 micrometers or less.
20. (Currently Amended) The adhesive-applied IC chip according to ~~Claims 15 to 19~~ Claim 15, wherein the adhesive material has substantially the same size as that of the IC chip.

21. (New) The electronic member fabricating method according to Claim 2, wherein the thermosetting adhesive material has a viscosity of 100 Pa·s or more at the attaching temperature during the adhesive material attaching process.
22. (New) The electronic member fabricating method according to Claim 5, wherein the thermosetting adhesive material has a viscosity of 100 Pa·s or more at the attaching temperature during the adhesive material attaching process.
23. (New) The electronic member fabricating method according to Claim 2, wherein the thermosetting adhesive material does not start the heat curing reaction at the attaching temperature during the adhesive material attaching process.
24. (New) The electronic member fabricating method according to Claim 5, wherein the thermosetting adhesive material does not start the heat curing reaction at the attaching temperature during the adhesive material attaching process.
25. (New) The electronic member fabricating method according to Claim 2, wherein the attaching temperature during the adhesive material attaching process is lower than the temperature that starts heat curing of the thermosetting adhesive material.
26. (New) The electronic member fabricating method according to Claim 5, wherein the attaching temperature during the adhesive material attaching process is lower than the temperature that starts heat curing of the thermosetting adhesive material.
27. (New) The electronic member fabricating method according to Claim 2, wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the mounting process.
28. (New) The electronic member fabricating method according to Claim 5, wherein the thermosetting adhesive material has a viscosity of 20000 Pa·s or less at the attaching temperature during the mounting process.
29. (New) The electronic member fabricating method according to Claim 27, wherein the thermosetting adhesive material has a viscosity of 100 Pa·s or more at the attaching temperature during the mounting process.

30. (New) The electronic member fabricating method according to Claim 28, wherein the thermosetting adhesive material has a viscosity of 100 Pa·s or more at the attaching temperature during the mounting process.
31. (New) The electronic member fabricating method according to Claim 2, wherein the thermosetting adhesive material does not start the heat curing reaction at the attaching temperature during the mounting process.
32. (New) The electronic member fabricating method according to Claim 5, wherein the thermosetting adhesive material does not start the heat curing reaction at the attaching temperature during the mounting process.
33. (New) The electronic member fabricating method according to Claim 2, further comprises a process for heating the thermosetting adhesive material to cause the heat curing reaction, after the mounting process.
34. (New) The electronic member fabricating method according to Claim 5, further comprises a process for heating the thermosetting adhesive material to cause the heat curing reaction, after the mounting process.
35. (New) The electronic member fabricating method according to Claim 2, wherein the thermosetting adhesive material is of a film type or a paste type.
36. (New) The electronic member fabricating method according to Claim 5, wherein the thermosetting adhesive material is of a film type or a paste type.
37. (New) The electronic member fabricating method according to Claim 2, wherein a dicing saw is used in the cutting process.
38. (New) The electronic member fabricating method according to Claim 5, wherein a dicing saw is used in the cutting process.